



2822

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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TC 2820 MAIL ROOM

**In re Application of:**

David R. Hembree

**Serial No.:** 09/834,297

**Filed:** April 12, 2001

**For:** CHIP ON BOARD WITH HEAT SINK  
ATTACHMENT

**Examiner:** J. Mitchell

**Group Art Unit:** 2822

**Attorney Docket No.:** 3592.5US (97-321.5)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

March 1, 2002  
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Deidra Pfeil  
Typed/printed name of person whose signature is contained above

H9  
Supplemental  
Citation  
5-1502

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the document listed on attached Form PTO-1449 or PTO/SB/08A be considered by the Examiner and made of record. The listed document is from co-pending application Serial No. 09/511,609, filed February 23, 2000. A copy of the listed document is enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56(b) exists.

DOCUMENTS

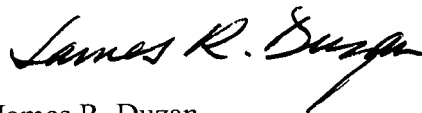
U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Issue Date</u>	<u>Inventor</u>
5,663,106	09/1997	Karavakis et al.

Applicant offers to supply any explanation or discussion of the document which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits. I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement.

Respectfully submitted,



James R. Duzan  
Registration No. 28,393  
Attorney for Applicant  
TRASKBRITT  
P. O. Box 2550  
Salt Lake City, Utah 84110-2550  
Telephone: (801) 532-1922

Date: March 1, 2002

JRD/sls:djp

Enclosures: Form PTO-1449 or PTO/SB/08A  
Copy of documents cited